US Headquarters 2950 Red Hill Ave, Costa Mesa California, USA 92626 Office: 714.913.2200 Fax: 714.913.2202 www.vikingtechnology.com

Datasheet for:

SDHC/SDXC UHS104 SD Cards

VTSD3xxxxCxxxxxC

SD Cards for Client Applications

Legal Information

Copyright© 2017 Sanmina Corporation. All rights reserved. The information in this document is proprietary and confidential to Sanmina Corporation. No part of this document may be reproduced in any form or by any means or used to make any derivative work (such as translation, transformation, or adaptation) without written permission from Sanmina. Sanmina reserves the right to revise this documentation and to make changes in content from time to time without obligation on the part of Sanmina to provide notification of such revision or change.

Sanmina provides this documentation without warranty, term or condition of any kind, either expressed or implied, including, but not limited to, expressed and implied warranties of merchantability, fitness for a particular purpose, and non-infringement. While the information contained herein is believed to be accurate, such information is preliminary, and should not be relied upon for accuracy or completeness, and no representations or warranties of accuracy or completeness are made. In no event will Sanmina be liable for damages arising directly or indirectly from any use of or reliance upon the information contained in this document. Sanmina may make improvements or changes in the product(s) and/or the program(s) described in this documentation at any time.

Sanmina, Viking Technology, Viking Modular Solutions, and the Viking logo are trademarks of Sanmina Corporation. Other company, product or service names mentioned herein may be trademarks or service marks of their respective owners.

Revision History

Date	Revision	Description	Checked by
2/21/17	А	Initial release.	
3/31/17	В	Revised format	

Ordering Information for the SDHC/SDXC UHS104 SD Cards

VikingPart#	Interface	Temp	GB	Client/Ent	NAND
VTSD3032GCCBMTLC	SD Card	(0to+70'c)	32GB (SDHC)	Client	TSB 15nm MLC
VTSD3064GCCAMTLC	SD Card	(0to+70'c)	64GB (SDXC)	Client	TSB 15nm MLC
VTSD3128GCCZMTLC	SD Card	(0to+70'c)	128GB (SDXC)	Client	TSB 15nm MLC

Notes:

- 1. Contact Viking for availability date
- 2. The lowercase letters x,y and z are wildcard characters that indicate product or customer specific information
- 3. Refer to the Viking part number coversheet or PN decoder for details.

Table of Contents

1	INTRODUCTION						
1.1	FEATURES						
2	SD CARD STANDARDS COMPATIBILITY						
3	PHYSICAL CHARACTERISTICS	9					
3.1	Environmental Characteristics	9					
3.2	Physical Characteristics	10					
4	ELECTRICAL INTERFACE	10					
4.1	Pin Assignment	10					
4.2	SD Card Bus Topology	11					
4.2	.1 SD Bus Mode protocol	12					
4.3	Initialization	18					
4.4	Electrical Characteristics	22					
	.1 Absolute Maximum Conditions .2 DC Characteristics	22					
	.3 AC Characteristics (Default Speed)	22 26					
	.4 AC Characteristics (Default Speed)	28					
	.5 AC Characteristics (Ultra High Speed; UHS104)	29					
5	CARD INTERNAL INFORMATION	34					
5.1	Security Information	34					
5.2	SD Card Registers	34					
5.2		35					
5.2		36					
	.3 CSD Register	36					
5.2		38					
5.2 5.2		38 38					
5.2 5.2		38					
5.2		40					
5.2		41					
5.3	Logical Format	42					
5.3	· · · · · · · · · · · · · · · · · · ·	43					
5.3		43					
5.3	.3 Data of the logical format of a 128GB Card	43					

	5.3.4 5.3.5	Data of the logical format of a 64GB Card Data of the logical format of a 32GB Card	43 43
6	SD	SPECIFICATION COMPLIANCE	43
7	RE	LIABILITY GUIDANCE	44
8	SD	CARD MECHANICAL DIMENSIONS	46

Table of Tables

Table 1-1: Features	8
Table 4-1: SD Card Pin Assignment	11
Table 4-2: SD Mode Command Set (+ = Implemented, - = Not Implemented)	13
Table 4-3: SPI Mode Command Set (+ = Implemented, - = Not Implemented)	
Table 4-4:S18R and S18A Combinations	
Table 4-5: Absolute Maximum Conditions	22
Table 4-6: DC Characteristics	
Table 4-7: Bus Operating Conditions - Signal Line's Load	25
Table 4-8: Threshold Level 1.8V Signaling	
Table 4-9: Threshold Level 1.8V Signaling	0.0
Table 4-10: Bus Timing - Parameters Values (Default Speed)	
Table 4-11: Bus Timing - Parameters Values (High Speed)	28
Table 4-12: Clock Signal Timing of SDR104, SDR50, SDR25, SDR12	30
Table 4-13: Clock input Timing of SDR104, SDR50, SDR25, SDR12	30
Table 4-14: Output Timing of Fixed Data Window (SDR50, SDR25, SDR12)	31
Table 4-15: Output Timing of Variable Data Window (SDR104)	32
Table 4-16: Clock Signal Timing of DDR50	
Table 4-17: BUS Timings – Parameters Values (DDR50 mode)	
Table 5-1: SD card Registers	
Table 5-2: OCR register definition	
Table 5-3: CID register	36
Table 5-4: CSD register	36
Table 5-5: The SCR Fields	38
Table 5-6: Card Status	38
Table 5.7. OD 0(a)	40
Table 5-7: SD Status	
Table 5-9: SD Card capacities	
	<i>4</i> 3
Table 6 16. 65 Gard Gystom Information	10
Table of Figures	
Figure 1-1: Top View	9
Figure 3-1: Write Protect Tab Polarity (Front View)	
Figure 4-1: SD Card Pin Assignment (Back view of the Card)	10
Figure 4-2: Bus Connection Diagram (SD Mode)	
Figure 4-3: Bus Connection Diagram (SPI Mode)	
Figure 4-4: UHS-I Host Initialization Flow Chart	10 19
Figure 4-5: ACMD41 Timing Followed by Signal Voltage Switch Sequence	
Figure 4-6: Signal Voltage Switch Sequence	13 21
Figure 4-7: SD Card Connection Diagram	
Figure 4-9: Card Output Timing (Default Speed Mode)	
Figure 4-10: Card Input Timing (High Speed Card)	
Figure 4-11: Card Output Timing (High Speed Card)	
Figure 4-12: Clock Input Timing	
Figure 4-13: Clock Input Timing	30
Figure 4-15: Output Timing of Variable WindowFigure 4-16: Clock Signal Timing	
Figure 4-16: Clock Signal Timing	32
rigure 4- m. mining Diagram DAT impuls/Outputs Referenced to CLN in DDR50 Mode	33

1 Introduction

This data sheet describes the specifications of the SDHC/SDXC Standard Card with UHS104 SD Bus mode. The SDHC/SDXC Cards are a Memory Card of Small and Thin with SDMI compliant Security method. (SDMI: Secure Digital Music Initiative) Contents in the Card can be protected by CPRM based security. This contents security can be accomplished by SDHC/SDXC Card, host, and security application software combinations.

1.1 FEATURES

Table 1-1: Features

Media Format	
SD Memory Card Standard	Compliant with the SD Memory Card Standard Ver. 4.20, UHS104
Security Functions	SD Security Specification Ver.3.00 Compliant (CPRM Based) *CPRM: Contents Protection for Recording Media Specification
Logical Format	SD File System Specification Ver.3.00 Compliant SDHC Card = FAT32, SDXC Card = exFAT
Electrical Features	
Operating Voltage	VDD = 2.7V(min), 3.3V(Typ), 3.6V(max)
Operating Current	SDR104 Write: 140mA(max) SDR104 Read: 150mA(max)
SD Interface	DS : Signaling Voltage = 3.3V(Typ), SDCLK = 25MHz HS : Signaling Voltage = 3.3V(Typ), SDCLK = 50MHz
UHS-I Interface	UHS104 : Signaling Voltage = 1.8V(Typ), SDCLK = 208MHz UHS50 : Signaling Voltage = 1.8V(Typ), SDCLK = 100MHz@SDR100 / 50MHz@DDR50 Supported UHS-I bus modes are SDR104, SDR50, DDR50, SDR25, SDR12.
Physical Features	
Physical Package size /Mass	L: 32, W: 24, T: 2.1 (mm), Weight: 1.8g (typ.) SD Physical Layer Specification Ver.4.10 Compliant
Durability	Compliant with SD Physical Layer Specification Ver.4.10 and Standard Size SD Card Mechanical Addendum Version 4.10.
RoHS	Compliant with RoHS regulations (DIRECTIVE 2011/65/EU)
Performance Features	
Maximum access speed	Sequential Write = 75 MB/s Sequential Read = 95 MB/s
Speed Class	UHS Speed Class = U3 SD Speed Class = C10



Figure 1-1: Top View

2 SD Card Standards Compatibility

This SD Memory Card Specification is compliant with:

- PHYSICAL LAYER SPECIFICATION Ver.4.20 (Part1) (Except for Mechanical Specification)
- FILE SYSTEM SPECIFICATION Ver.3.00. (Part2)
- SECURITY SPECIFICATION Ver.3.00. (Part3)
- Standard Size SD Card Mechanical Addendum Version 4.10

3 Physical Characteristics

3.1 Environmental Characteristics

The standard Operation Conditions are:

- Absolute Maximum Temperature Range Ta = -25 to +85°C
- Humidity less than RH = 95 %, Non condensed Ta = 25°C

The standard Storage Conditions are:

- Maximum Temperature Range:
 Tstg = -40 to +85°C
- Humidity less than RH = 93%, Non condensed
 Ta = 40°C

3.2 Physical Characteristics

Mechanical Write Protect Switch

A mechanical sliding tab on the side of the card can be used as a write protect switch. The host system shall be responsible for this function.

The card is in a "Write Protected" status when the tab is located on the "Lock "position. The host system shall not write nor format the card in this status.

The card is in "Write Enabled" status when the tab is moved to the opposite position (Un-Lock). (Please refer the figures below for the tab polarity.)

Please slide the tab until a dead end (stopped position). The tab is set on the "Write Enabled" position when it is shipped.

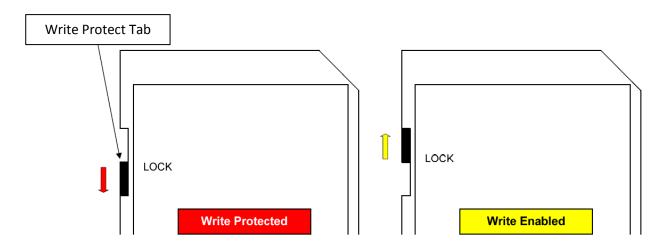


Figure 3-1: Write Protect Tab Polarity (Front View)

4 Electrical Interface

4.1 Pin Assignment

The table below describes the pin assignment of the SD card. The following figure describes the pin assignment of the SD card. Please refer the detail descriptions by SD Card Physical Layer Specification.

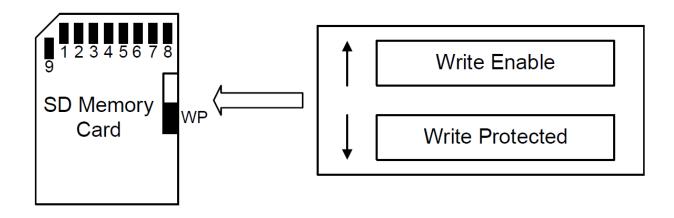


Figure 4-1: SD Card Pin Assignment (Back view of the Card)

Table 4-1: SD Card Pin Assignment

	SD Mode				SPI	Mode
Pin	Name	IO Type	Description	Name	ІО Туре	Description
1	CD/ DAT3	I/O/ PP	Card Detect/ Data Line[Bit3]	cs	I	Chip Select (Negative True)
2	CMD	PP	Command/Response	DI	I	Data In
3	Vss1	S	Ground	Vss	S	Ground
4	Vdd	S	Supply Voltage	V _{DD}	S	Supply Voltage
5	CLK	I	Clock	SCLK	I	Clock
6	Vss2	S	Ground	Vss2	S	Ground
7	DAT0	I/O/PP	Data Line[Bit0]	DO	O/PP	Data Out
8	DAT1	I/O/PP	Data Line[Bit1]	RSV	_	Reserved(*)
9	DAT2	I/O/PP	Data Line[Bit2]	RSV	_	Reserved(*)

Notes:

S: Power Supply

O: Output using push-pull drivers

4.2 SD Card Bus Topology

The device supports two alternative communication protocols: SD and SPI Bus Mode. It is as same as standard SD memory card. Host System can choose either one of modes. Same Data of the device can read and write by both modes. SD Mode allows the 4-bit high performance data transfer. SPI Mode allows easy and common interface for SPI channel. The disadvantage of this mode is loss of performance, relatively to the SD mode.

I: Input

PP: I/O using push-pull drivers

^(*) These signals should be pulled up by host side with 10-100k ohm resistance in the SPI Mode.

4.2.1 SD Bus Mode protocol

The SD bus allows the dynamic configuration of the number of data line from 1 to 4 Bidirectional data signal. After power up by default, the Device will use only DATO. After initialization, host can change the bus width. Multiplied SD cards connections are available to the host. Common VDD, VSS and CLK signal connections are available in the multiple connections. However, Command, Respond and Data lined (DATO-DAT3) shall be divided for each card from host. This feature allows easy tradeoff between hardware cost and system performance. Communication over the SD bus is based on command and data bit stream initiated by a start bit and terminated by stop bit.

Command:

Commands are transferred serially on the CMD line. A command is a token to starts an operation from host to the card. Commands are sent to an addressed single card (addressed Command) or to all connected cards (Broad cast command).

Response:

Responses are transferred serially on the CMD line. A response is a token to answer to a previous received command. Responses are sent from an addressed single card or from all connected cards.

Data:

Data can be transfer from the card to the host or vice versa. Data is transferred via the data lines.

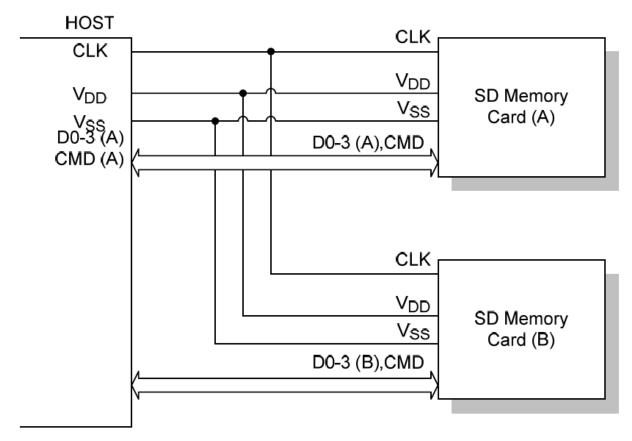


Figure 4-2: Bus Connection Diagram (SD Mode)

CLK Host card Clock signal

CMD Bi-directional Command/ Response Signal

DAT0 - DAT3 4 Bi-directional data signal

VDD Power supply

VSS GND

Table 4-2: SD Mode Command Set (+ = Implemented, - = Not Implemented)

CMD Index	Abbreviation	Implementation	Note
CMD0	GO_IDLE_STATE	+	
CMD2	ALL_SEND_CID	+	
CMD3	SEND_RELATIVE_ADDR	+	
CMD4	SET_DSR	-	DSR Register is not implemented.
CMD6	SWITCH_FUNC	+	
CMD7	SELECT/DESELECT_CARD	+	
CMD8	SEND_IF_COND	+	
CMD9	SEND_CSD	+	
CMD10	SEND_CID	+	
CMD11	VOLTAGE_SWITCH	+	UHS-I mode

CMD Index	Abbreviation	Implementation	Note
CMD12	STOP_TRANSMISSION	+	
CMD13	SEND_STATUS	+	
CMD15	GO_INACTIVE_STATE	+	
CMD16	SET_BLOCKLEN	+	
CMD17	READ_SINGLE_BLOCK	+	
CMD18	READ_MULTIPLE_BLOCK	+	
CMD19	SEND_TUNING_PATTERN	+	UHS-I mode
CMD20	SPEED_CLASS_CONTROL	+	
CMD23	SET_BLOCK_COUNT	+	
CMD24	WRITE_BLOCK	+	
CMD25	WRITE_MULTIPLE_BLOCK	+	
CMD26	Reserved for Manufacturer	+	
CMD27	PROGRAM_CSD	+	
CMD28	SET_WRITE_PROT	-	
CMD29	CLR_WRITE_PROT	-	Internal Write Protection is not implemented.
CMD30	SEND_WRITE_PROT	-	
CMD32	ERASE_WR_BLK_START	+	
CMD33	ERASE_WR_BLK_END	+	
CMD38	ERASE	+	
CMD42	LOCK_UNLOCK	+	
CMD55	APP_CMD	+	
CMD56	GEN_CMD	+	This command is not specified.
CMD60	Reserved for Manufacturer	+	
CMD61	Reserved for Manufacturer	+	
CMD62	Reserved for Manufacturer	+	
ACMD6	SET_BUS_WIDTH	+	
ACMD13	SD_STATUS	+	
ACMD22	SEND_NUM_WR_BLOCKS	+	
ACMD23	SET_WR_BLK_ERASE_COUNT	+	
	SD_SEND_OP_COND	+	1.8V Signaling and XPC (SDXC Power Control) support
ACMD42	SET_CLR_CARD_DETECT	+	
	SEND_SCR	+	
ACMD18	SECURE_READ_MULTI_BLOCK	+	
ACMD25	SECURE_WRITE_MULTI_BLOCK	+	
ACMD26	SECURE_WRITE_MKB	+	
ACMD38	SECURE_ERASE	+	
	GET_MKB	+	
	GET_MID	+	
ACMD45	SET_CER_RN1	+	
ACMD46	GET_CER_RN2	+	
ACMD47	SET_CER_RES2	+	
ACMD48	GET_CER_RES1	+	
	CHANGE_SECURE_AREA	-	
Notes:	•	•	•

Notes:

- CMD28, 29 and CMD30 are optional commands.
- CMD4 is not implemented because DSR register (Optional Register) is not implemented.
- CMD56 is a vender specific command which is not defined in the standard card.

6.2.2 SPI Bus mode Protocol

The SPI bus allows 1 bit Data line by 2-chanel (Data In and Out). The SPI compatible mode allows the MMC Host systems to use SD card with little change. The SPI bus mode protocol is byte transfers. All the data token are multiples of the bytes (8-bit) and always byte aligned to the CS signal.

The advantage of the SPI mode is reducing the host design effort. Especially, the MMC host can be modified with little change. The disadvantage of the SPI mode is the loss of performance versus SD mode.

Caution: Please use SD Card Specification. DO NOT use MMC Specification. (For example, initialization is achieved by ACMD41, and be careful to Register. Register definition is different, especially CSD Register.)

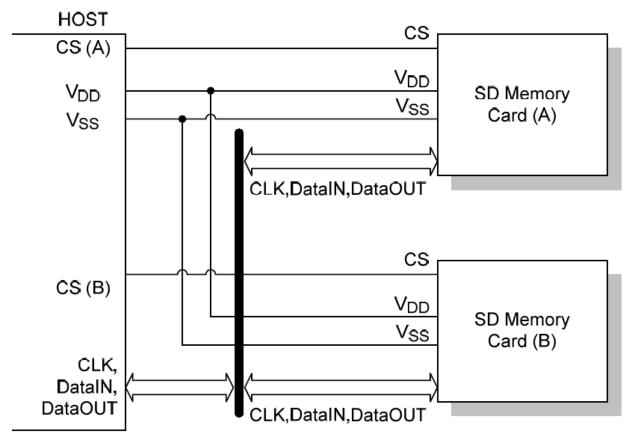


Figure 4-3: Bus Connection Diagram (SPI Mode)

CS Card Select Signal
CLK Host card Clock signal

CMD Bi-directional Command/ Response Signal

DataIN Host to card data line
DataOUT Host to card data line
VDD Power supply

GND

Table 4-3: SPI Mode Command Set (+ = Implemented, - = Not Implemented)

VSS

CMD Index	Abbreviation	Implementation	Note
CMD0	GO_IDLE_STATE	+	
CMD1	SEND_OP_COND	+	
CMD6	SWITCH_FUNC	+	
CMD8	SEND_IF_COND	+	
CMD9	SEND_CSD	+	
CMD10	SEND_CID	+	
CMD12	STOP_TRANSMISSION	+	
CMD13	SEND_STATUS	+	
CMD16	SET_BLOCKLEN	+	

CMD Index	Abbreviation	Implementation	Note
CMD17	READ_SINGLE_BLOCK	+	
CMD18	READ_MULTIPLE_BLOCK	+	
CMD24	WRITE_BLOCK	+	
CMD25	WRITE_MULTIPLE_BLOCK	+	
CMD26	Reserved for Manufacturer	+	
CMD27	PROGRAM_CSD	+	
CMD28	SET_WRITE_PROT	-	
CMD29	CLR_WRITE_PROT	-	Internal Write Protection is not implemented.
CMD30	SEND_WRITE_PROT	-	
CMD32	ERASE_WR_BLK_START	+	
CMD33	ERASE_WR_BLK_END	+	
CMD38	ERASE	+	
CMD42	LOCK_UNLOCK	+	
CMD55	APP_CMD	+	
CMD56	GEN_CMD	+	This command is not specified.
CMD58	READ_OCR	+	
CMD59	CRC_ON_OFF	+	
	Reserved for Manufacturer	+	
ACMD13	SD_STATUS	+	
ACMD22	SEND_NUM_WR_BLOCKS	+	
ACMD23	SET_WR_BLK_ERASE_COUNT	+	
ACMD41	SD_SEND_OP_COND	+	
ACMD42	SET_CLR_CARD_DETECT	+	
ACMD51	SEND_SCR	+	
ACMD18	SECURE_READ_MULTI_BLOCK	+	
ACMD25	SECURE_WRITE_MULTI_BLOCK	+	
ACMD26	SECURE_WRITE_MKB	+	
ACMD38	SECURE_ERASE	+	
ACMD43	GET_MKB	+	
ACMD44	GET_MID	+	
ACMD45	SET_CER_RN1	+	
ACMD46	GET_CER_RN2	+	
ACMD47	SET_CER_RES2	+	
ACMD48	GET_CER_RES1	+	

Notes:

- CMD28, 29 and CMD30 are optional commands.
- CMD56 is a vender specific command which is not defined in the standard card.

4.3 Initialization

The following figures show the initialization flow chart for UHS-I hosts and the sequence of commands to perform a signal voltage switch. Red and yellow boxes are new procedures to initialize the UHS-I card.

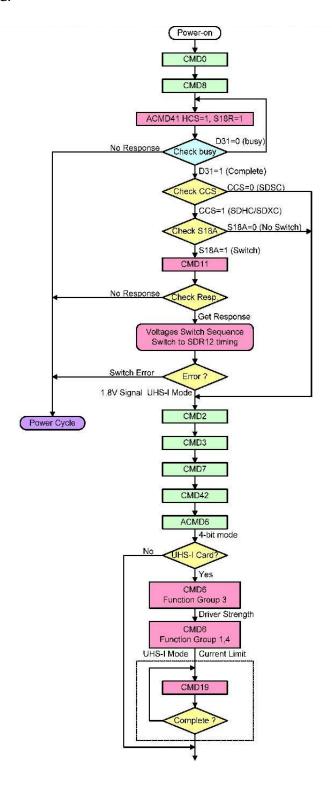


Figure 4-4: UHS-I Host Initialization Flow Chart

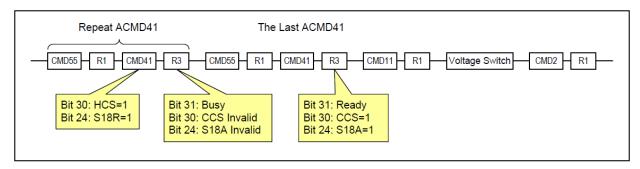


Figure 4-5: ACMD41 Timing Followed by Signal Voltage Switch Sequence

1) POWER ON: Supply Voltage for initialization.

Host System applies the perating Voltage to the card. Apply more than 74 cycles of Dummy-clock to the SD card.

2) Select operation mode (SD mode or SPI mode)

In the case of SPI mode operation, the host should drive pin 1 (CD/DAT3) of the SD Card I/F to a "Low" level. Then, issue CMD0. In the case of SD mode operation, the host should drive or detect pin 1 of the SD Card I/F (Pull up register of pin 1 is pull up to "High" normally). The card maintains selected operation mode except re-issue of CMD0 or power on below is SD mode initialization procedure.

3) Send Interface condition command (CMD8).

When the card is in the Idle state, the host shall issue CMD8 before ACMD41. In the argument, 'voltage supplied' is set to the host supply voltage and 'check pattern' is set to any 8-bit pattern. The card that accepted the supplied voltage returns R7 response. In the response, the card echoes back both the voltage range and check pattern set in the argument. If the card does not support the host supply voltage, it shall not return response and stays in the Idle state.

4) Send initialization command (ACMD41).

When the signaling level is 3.3V, the host repeats an issue ACMD41 with HCS=1 and S18R=1 until the response indicates ready. The argument (HCS and S18R) of the first ACMD41 is effective but the all the following ACMD41 should be issued with the same argument. If Bit 31 indicates ready, the host needs to check CCS and S18A. The card indicates S18A=0, which means that the voltage switch is not allowed and the host needs to use the current signaling level.

Table 4-4:S18R and S18A Combinations

Current Signaling Level	18R	S18A	Comment	
	0	0	1.8V signaling is not requested	
3.3V	1	0	The card does not support 1.8V signaling	
	1	1	Start signal voltage switch sequence	
1.8V	Х	0	Already switched to 1.8V	

5) Send voltage switch command (CMD11)

S18A=1 means that the voltage switch is allowed and host issues CMD11 to invoke voltage switch sequence. By receiving CMD11, the card returns R1 response and start voltage switch sequence. No response of CMD11 means that S18A was 0 and therefore the host should not have sent CMD11. Completion of voltage switch sequence is checked by high level of DAT[3:0]. Any bit of DAT[3:0] can be checked depends on ability of the host. The card enters UHS-I mode and card input and output timings are changed (SDR12 in default) when the voltage switch sequence is completed successfully.

6) Send ALL_SEND_CID command (CMD2) and get the Card ID (CID)

7) Send SEND RELATIVE ADDR (CMD3) and get the RCA. RCA value is randomly changed by access, not equal zero.

8) Send SELECT / DESELECT_CARD command (CMD7) and move to the transfer state. When entering tran state, CARD_IS_LOCKED status in the R1 response should be checked (it is indicated in the response of CMD7). If the CARD_IS_LOCKED status is set to 1 in the response of CMD7, CMD42 is required before ACMD6 tounlock the card. (If the card is locked, CMD42 is required to unlock the card.) If the card is unlocked, CMD42 can be skipped.

9) Send SET_BUS_WIDTH command (ACMD6).

UHS-I supports only 4-bit mode. Host shall select 4-bit mode by ACMD6. If the card is locked, host needs to unlock the card by CMD42 in 1-bit mode and then needs to issue ACMD6 to change 4-bit bus mode. Operating in 1-bit mode is not assured.

10) Set driver strength.

CMD6 mode 0 is used to query which functions the card supports, and to identify the maximum current consumption of the card under the selected functions. In case of UHS-I card, appropriate driver strength (default is Type-B buffer) is selected by CMD6 Function Group 3.

11) Set UHS-I mode current limit.

UHS-I modes (Bus Speed Mode) is selected by CMD6 Function Group
1. Current limit is selected by CMD6 Function Group 4.

Maximum access settings: SDR104 = (CMD6 Function Group 1 = 3-h, CMD6 Function Group 4 = 0-h(*)) SDR50 = (CMD6 Function Group 1 = 2-h, CMD6 Function Group 4 = 0-h(*)) DDR50 = (CMD6 Function Group 1 = 4-h, CMD6 Function Group 4 = 0-h(*)) (*) The Current Limit is default value (200mA).

Note:

Function Group 4 is defined as Current Limit switch for SDR50, SDR104. The Current Limit does not act on the card in SDR12 and SDR25. The default value of the Current Limit is 200mA (minimum setting). Then after selecting one of SDR50, SDR104 mode by Function Group 1, host needs to change the Current Limit to enable the card to operate in higher performance. This value is determined by a host power supply capability to the card, heat release method taken by a host and the maximum current of a connector.

12) Tuning of sampling point

CMD19 sends a tuning block to the host to determine sampling point. In SDR50 and SDR104 modes, if tuning of sampling point is required, CMD19 is repeatedly issued until tuning is completed. Then the Host can access the Data between the SD card as a storage device.

Application Notes:

- 1.The host shall set ACMD41 timeout to more than 1 second to abort repeat of issuing ACMD41 when the card does not indicate ready. The timeout count starts from the first ACMD41 which is set voltage window in the argument.
- 2.Once the signal voltage is switched to 1.8V, the card continues 1.8V signaling regardless of CMD0. Power cycle resets the signal voltage to 3.3V. After switching 1.8V singling, the card cannot be changed to SPI mode.
- 3. Timing to Switch Signal Voltage To change signaling level at the same time between host and card, signal voltage switch sequence is invoked by CMD11 as shown in the figure below. CMD11 is issued only when S18A=1 in the response of ACMD41.

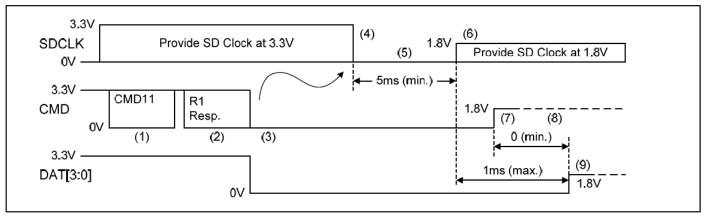


Figure 4-6: Signal Voltage Switch Sequence

Steps that the host takes to start a voltage switch sequence.

- 1. The host issues CMD11 to start voltage switch sequence.
- 2. The card returns R1 response.
- 3. The card drives CMD and DAT[3:0] to "low" immediately after the response.
- 4. The host stops supplying SDCLK. The card shall start switching voltage after host stops SDCLK. The time to stop SDCLK is not specified. The host can detect whether the sequence starts by checking signal level of either one of CMD, DAT[3:0]. What signal should be checked will depend on the ability of the host. If low level is not detected, the host should abort the sequence and execute power cycle.

- 5. 1.8V output of voltage regulator in card shall be stable within 5ms. The Host keeps SDCLK low at least 5ms. This means that 5ms is the maximum for the card and the minimum for the host.
- 6. After 5ms from (step 4) and host voltage regulator is stable, the host starts providing SDCLK at 1.8V. The card can check whether SDCLK voltage is 1.8V.
- 7. By detecting SDCLK, the card drives CMD to high at 1.8V for at least one clock and then stops driving (tri-state). CMD is triggered by rising edge of SDCLK (SDR timing).
- 8. The card can check whether host drives CMD to 1.8V through the host pull-up resister.
- 9. If switching to 1.8V signaling is completed successfully, the card drives DAT[3:0] to high at 1.8V at least one clock and then stop driving (tri-state). DAT[3:0] is triggered by rising edge of SDCLK (SDR timing). DAT[3:0] shall be high within 1ms from start of providing SDCLK. Host check whether DAT[3:0] is high after 1ms from supplying SDCLK. This means that 1ms is the maximum for the card and the minimum for the host.

4.4 Electrical Characteristics

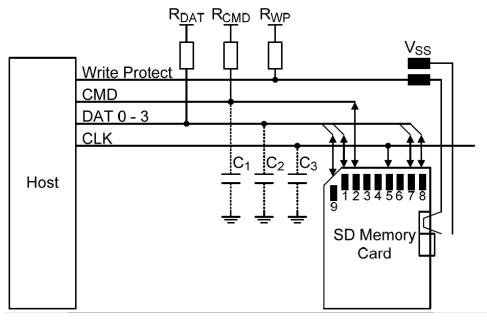


Figure 4-7: SD Card Connection Diagram

4.4.1 Absolute Maximum Conditions

Table 4-5: Absolute Maximum Conditions

Item	Symbol	Value	Unit
Supply Voltage	V _{DD}	-0.3 to 3.9	V
Input Voltage	Vin	-0.3 to V _{DD} +0.3 (≤3.9)	V

4.4.2 DC Characteristics

Table 4-6: DC Characteristics

Item	Symbol	Condition	MIN.	Тур.	MAX.	Unit	Note
Supply Voltage	V _{DD}	-	2.7	-	3.6	V	

Item			Symbol	Condition	MIN.	Тур.	MAX.	Unit	Note
		High Level	.,		\/ +0.00F			V	
	Input Voltage	Low	VIH VIL		VDD*0.625	<u>-</u>	- V _{DD} *0.25	V	
	voltago	High Level	Vон	Iон = - 2mA	VDD*0.75	-	-	V	
3.3V Signaling	Output Voltage	Low Level	Vol	loL = 2mA	-	-	V _{DD} *0.125	V	
		High Level	Vıн	-	1.27		2	V	
	Input Voltage	Low Level	VIL		-	-	0.58	V	
		High Level	Vон	Iон = - 2mA	1.4	-	-	V	
1.8V Signaling	Output Voltage	Low Level	Vol	loL = 2mA	-	-	0.45	V	
		32GB					400		
		64GB	-	V _{DD} = 3.6V	-	-	450		
Standby Co	urrent	128GB	lccs	Clock Stop	-	-	650	uA	Ta=25°C
				SDR104 Current Limit = 200mA, 400mA VDD= 3.6V			170		
				SDR50 Current Limit = 200mA, 400mA V _{DD} = 3.6V	-		170		
				DDR50 Current Limit = 200mA, 400mA VDD = 3.6V	-	-	155		
				SDR25, HS V _{DD} = 3.6V	-	-	135		
Operation Current (pe		32GB 64GB 128GB	Iccop1 1	SDR12, DS V _{DD} = 3.6V	-	-	125	mA	Ta=25°C

ltem			Symbol	Condition	MIN.	Тур.	MAX.	Unit	Note
				SDR104 Current Limit = 200mA, 400mA VDD= 3.6V					
				00050	-	-	220	-	
				SDR50 Current Limit = 200mA, 400mA V _{DD} = 3.6V	_	_	205		
Operation \		32GB 64GB		DDR50 Current Limit = 200mA, 400mA VDD =					T 0500
Current (pe	ak)	128GB	ICCOP1 1	3.6V	-	-	205	mA	Ta=25°C
				SDR25, HS V _{DD} = 3.6V	-	-	145		
				SDR12, DS V _{DD} = 3.6V	_	_	140		
				SDR104 Current Limit = 200mA, 400mA VDD= 3.6V	_	_	130	mA	Ta=25°C
				SDR50 Current Limit = 200mA, 400mA VDD=	-	-		IIIA	1a=25 C
				3.6V DDR50 Current Limit = 200mA, 400mA VDD =	-	-	100		
				3.6V	-	-	95		
				SDR25, HS V _{DD} = 3.6V	-	-	80		
Operation Read Current (average)	32GB 64GB 128GB		ICCOP2 2	SDR12, DS V _{DD} = 3.6V	-	-	70		

Item		Symbol	Condition	MIN.	Тур.	MAX.	Unit	Note
			SDR104 Current Limit = 200mA, 400mA VDD= 3.6V					
			00050	-	-	145	mA	Ta=25°C
			SDR50 Current Limit = 200mA, 400mA V _{DD} = 3.6V	-	-	115		
			DDR50 Current Limit = 200mA, 400mA VDD = 3.6V	_	-	110		
			SDR25, HS V _{DD} = 3.6V	-	-	90		
Operation Write Current (average)	32GB 64GB 128GB	Iccop2 2	SDR12, DS V _{DD} = 3.6V	-	-	75		

Notes: Peak Current RMS value over a 10usec period. 2) Average Current value over 1second period.

Table 4-7: Bus Operating Conditions - Signal Line's Load

Parameter	Symbol	Min.	Max.	Unit	Remark
Pull-up resistance	RCMD RDAT	10	100	kΩ	To prevent bus floating
Total bus capacitance for each signal line	CL		40	pF	1 card Сноsт+Свиs shall not exceed 30 pF
Card capacitance for each signal pin	Ccard		10	pF	
Maximum signal line inductance			16	nΗ	
Pull-up resistance inside card (pin1)	R _{DAT3}	10	90	kΩ	May be used for card detection
Capacity Connected to Power Line	C c		5	uF	To prevent inrush current

Table 4-8: Threshold Level 1.8V Signaling

Parameter	Symbol	Min.	Max.	Unit	Remark
Supply Voltage	Vdd	2.70	3.60	V	
Regulator Voltage	Vddio	1.70	1.95	V	Generated by VDD
Output High Voltage	Vон	1.40	-	V	Ioн= -2mA
Output Low Voltage	Vol		0.45	V	IoL = 2mA
Input High Voltage	ViH	1.27	2.00	V	
Input Low Voltage	VIL	Vss-0.30	0.58	V	

Table 4-9: Threshold Level 1.8V Signaling

Parameter	Symbol	Min.	Max.	Unit	Remark
Input Leakage Current		-2	2	uA	DAT3 pull-up is disconnected.

4.4.3 AC Characteristics (Default Speed)

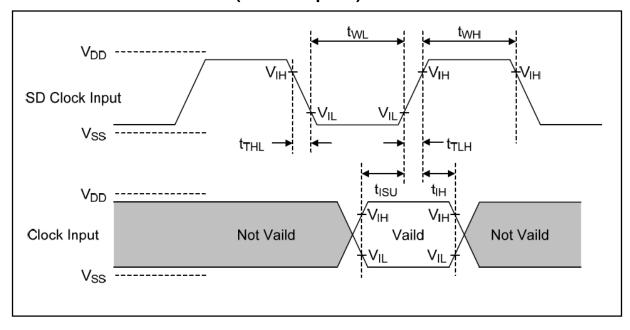


Figure 4-8: Card Input Timing (Default Speed Mode)

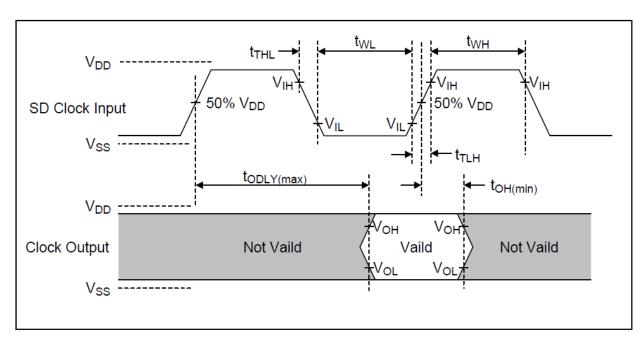


Figure 4-9: Card Output Timing (Default Speed Mode)

Table 4-10: Bus Timing - Parameters Values (Default Speed)

Parameter	Symbol	Min.	Max.	Unit	Remark				
Clock CLK (All values are referred to min (Vıн) and max	(VIL)							
Clock frequency Data Transfer Mode	fрр	0	25	MHz	Ccard ≤ 10 pF (1 card)				
Clock frequency Identification Mode	fod	0(1)/100	400	kHz	Ccard ≤ 10 pF (1 card)				
Clock low time	tw∟	10		ns	Ccard ≤ 10 pF (1 card)				
Clock high time	twн	10		ns	Ccard ≤ 10 pF (1 card)				
Clock rise time	tт∟н		10	ns	Ccard ≤ 10 pF (1 card)				
Clock fall time	tтнL		10	ns	Ccard ≤ 10 pF (1 card)				
Parameter	Symbol	Min.	Max.	Unit	Remark				
Inputs CMD, DAT (referenced to CLk	Inputs CMD, DAT (referenced to CLK)								
Input set-up time	tISU	5		ns	CCARD ≤ 10 pF (1 card)				
Input hold time	tlH	5		ns	CCARD ≤ 10 pF (1 card)				
Parameter	Symbol	Min.	Max.	Unit	Remark				
Outputs CMD, DAT (referenced to CI	_K)								
Output Delay time during Data Transfer Mode	tODLY	0	14	ns	CL ≤ 40 pF (1 card)				
Output Delay time during Identification Mode	tODLY	0	50	ns	CL ≤ 40 pF (1 card)				

Note:

^{1. 0} Hz means to stop the clock. The given minimum frequency range is for cases were continues clock is required

4.4.4 AC Characteristics (High Speed)

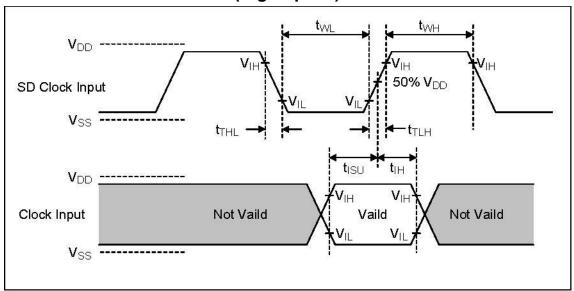


Figure 4-10: Card Input Timing (High Speed Card)

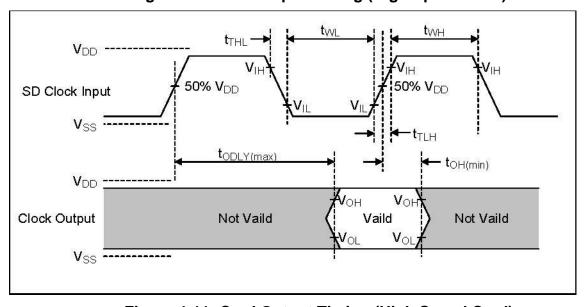


Figure 4-11: Card Output Timing (High Speed Card)

Table 4-11: Bus Timing - Parameters Values (High Speed)

Parameter	Symbol	Min.	Max.	Unit	Remark
Clock CLK (All values are ref	erred to m	nin (VIH	l) and m	nax (V	IL)
Clock frequency Data Transfer Mode	fрр	0	50	MHz	Ccard ≤ 10 pF (1 card)

Parameter	Symbol	Min.	Max.	Unit	Remark				
Clock low time	tw∟	7		ns	Ccard ≤ 10 pF (1 card)				
Clock high time	twн	7		ns	Ccard ≤ 10 pF (1 card)				
Clock rise time	tтьн		3	ns	Ccard ≤ 10 pF (1 card)				
Clock fall time	tтн∟		3	ns	Ccard ≤ 10 pF (1 card)				
Parameter	Symbol	Min.	Max.	Unit	Remark				
Inputs CMD, DAT (referenced to CLK)									
Input set-up time	tısu	6		ns	Ccard ≤ 10 pF (1 card)				
Input hold time	tıн	2		ns	Ccard ≤ 10 pF (1 card)				
Parameter	Symbol	Min.	Max.	Unit	Remark				
Outputs CMD, DAT (reference	ed to CLk	()							
Output Delay time during Data Transfer Mode	todly		14	ns	C∟ ≤ 40 pF (1 card)				
Output Hold time	tон	2.5		ns	CL > 15pF (1 card)				
Output Delay time during Identification Mode	todly	0	50	ns	C∟ ≤ 40 pF (1 card)				

4.4.5 AC Characteristics (Ultra High Speed; UHS104)

6.4.5.1 Bus Timing Specification <SDR104, SDR50,SDR25,SDR12>

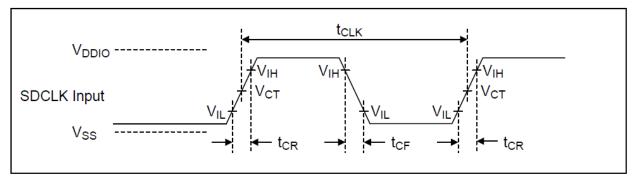


Figure 4-12: Clock Signal Timing

Table 4-12: Clock Signal Timing of SDR104, SDR50, SDR25, SDR12

Symbol	Min.	Max.	Unit	Remark
tclk	4.80	-	ns	208MHz (Max.), Between rising edge, Vc⊤= 0.975V
tcr, tcf	-	0.2* tCLK		tcr, tcr < 0.96ns (max.) at 208MHz, Ccard=10pF tcr, tcr, < 2.00ns (max.) at 100MHz, Ccard=10pF
Clock Duty	30	70	%	

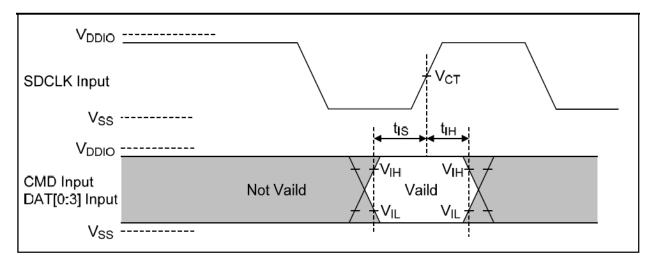


Figure 4-13: Clock Input Timing

Table 4-13: Clock input Timing of SDR104, SDR50, SDR25, SDR12

Symbol	Min.	Max.	Unit	SDR104 mode
tıs	1.40	-	ns	Ccard =10pF, Vct= 0.975V
tıн	0.80	-	ns	Ccard =5pF, Vct= 0.975V
Symbol	Min.	Max.	Unit	SDR12, SDR25 and SDR50 mode
Symbol tis	Min. 3.00	Max.	Unit ns	SDR12, SDR25 and SDR50 mode Ccard =10pF, Vct= 0.975V

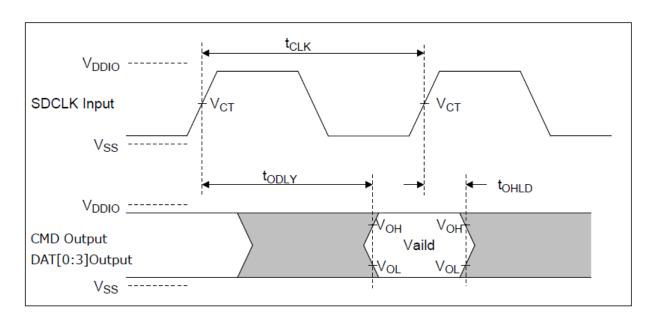


Figure 4-14: Output Timing of Fixed Window

Table 4-14: Output Timing of Fixed Data Window (SDR50, SDR25, SDR12)

Symbol		Min.	Max.	Unit	Remark				
todly	Т		7.5	ns	tclk>=10.0ns, Cl=30pF, using driver Type B, for SDR50				
todly			14	ns	tclk>=20.0ns, Cl=40pF, using driver Type B, for SDR25 and SDR12				
tон	T	1.5	-	ns	Hold time at the todly (min.), CL=15pF				

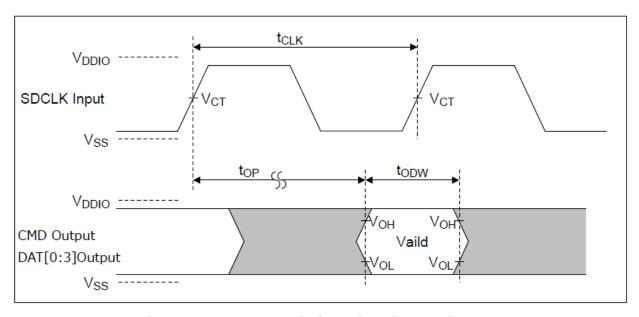


Figure 4-15: Output Timing of Variable Window

Table 4-15: Output Timing of Variable Data Window (SDR104)

Symbol	Min.	Max.	Unit	Remark			
top	0	2	UI	Card Output Phase			
Δtop	-350	+1550	ps	Delay variation due to temperature change after tuning			
todw	0.60	-	UI	topw=2.88ns at 208MHz			

Card ΔtOP is the total allowable shift of output valid window (tODW) from last system Tuning procedure. Card ΔtOP =1550pS for junction temperature of ΔT = 90°C during operation. Card ΔtOP =-350pS for junction temperature of ΔT = -20°C during operation.

6.4.5.2 Bus Timing Specification <DDR50>

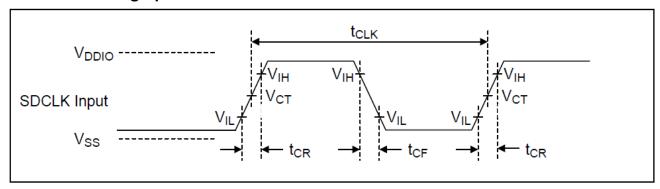


Figure 4-16: Clock Signal Timing

Table 4-16: Clock Signal Timing of DDR50

Symbol	Min.	Max.	Unit	Remark
tclk	20	-	ns	50MHz (Max.), Between rising edge
tcr, tcf	-	0.2* tськ	ns	tcr, tcr, < 4.00ns (max.) at 50MHz, Ccard=10pF
Clock Duty	45	55	%	

CMD signal timings are not shown in the figure below but For CMD signal timing refers to Figure 4-13 (Card Input Timing) and Figure 4-14 (Output Timing of Fixed Data Window) for Timing Diagram of SDR mode).

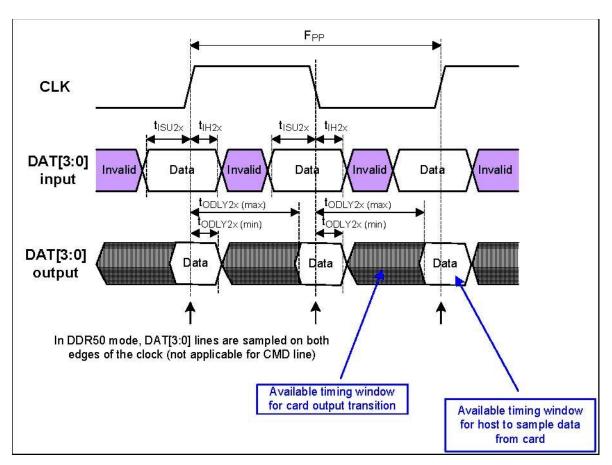


Figure 4-17: Timing Diagram DAT Inputs/Outputs Referenced to CLK in DDR50 Mode

Table 4-17: BUS Timings – Parameters Values (DDR50 mode)

Parameter	Symbol	Min	Max	Unit	Remark					
nput CMD (referenced to CLK rising edge)										
Input set-up time (*)	tısu	3	-	ns	Ccard ≤ 10 pF (1 card)					
Input hold time	tıн	0.8	-	ns	Ccard ≤ 10 pF (1 card)					
Output CMD (referenced to CL	K rising (edge))							
Output Delay time during Data Transfer Mode	t odly	-	13.7	ns	C∟ ≤ 30 pF (1 card)					
Output hold time	tон	1.5	-	ns	C∟ ≥ 15pF (1 card)					
Inputs DAT (referenced to CLK	rising a	nd fa	lling e	dge	s)					
Input set-up time	tısu2x	3	-	ns	Ccard ≤ 10 pF (1 card)					
Input hold time	tıH2x	0.8	-	ns	Ccard ≤ 10 pF (1 card)					
Outputs DAT (referenced to CL	.K rising	and f	alling	ı edg	es)					
Output Delay time during Data Transfer Mode	todly2x		7.0	ns	C∟ ≤ 25 pF (1 card)					
Output hold time	todly2x	1.5	-	ns	C∟ ≥ 15pF (1 card)					

^(*) Input set-up time: tISU(min) is 6ns in PHYSICAL LAYER SPECIFICATION Ver.3.01

5 Card Internal Information

5.1 Security Information

MKB (Media Key Block) and Media ID are Standard Information. This information is in compliance with the CPRM.

Note: The security information is NOT Development information for evaluation. The Host System shall be compliance with the CPRM to use the security function. This information is kept as confidential because of security reasons.

5.2 SD Card Registers

The device has six Registers and two Status information: OCR, CID, CSD, RCA, DSR, SCR and Card Status, SD Status as same as SD card.

DSR IS NOT SUPPORTED in this card.

There are two types of register groups.

- MMC compatible registers: OCR, CID, CSD, RCA, DSR, and
- SCR SD card Specific: SD Status and Card Status

Table 5-1: SD card Registers

Register Name	Bit Width	escription				
CID	128	Card Identification number				
RCA	16	Relative Card Address				
DSR	16	Optional : Driver Stage				
CSD	128	Card Specific Data				
SCR	64	SD Configuration				
OCR	32	Operation conditions				
SSR	512	SD Status				
CSR	32	Card Status				
CMD6	512	Switch Function Status				

5.2.1 OCR Register

This 32-bit register describes operating voltage range and status bit in the power supply.

Table 5-2: OCR register definition

OCR bit		D Fields Definition			Response Value
position		R Fields Definition	32GB		
0-3		reserved	0	0	0
4-6		reserved	0	0	0
7		Reserved for Low Voltage Range	0	0	0
8-14		reserved	0	0	0
15		2.7 - 2.8	1	1	1
16	VDD	2.8 - 2.9	1	1	1
17	voltage Window	2.9 - 3.0	1	1	1
18	vviilaow	3.0 - 3.1	1	1	1
19		3.1 - 3.2	1	1	1
20		3.2 - 3.3	1	1	1
21		3.3 - 3.4	1	1	1
22		3.4 - 3.5	1	1	1
23		3.5 - 3.6	1	1	1
24(1)	Switching to 1.8V Accepted (S18A)		1	1	1
25-29		reserved	0	0	0
30	Card C	Capacity Status (CCS)(2)	1 (SDHC)	1 (SDXC)	1 (SDXC)
31	Card po	wer up status bit (busy)(3)	" 0 " = busy " 1 " = ready	" 0 " = busy " 1 " = ready	" 0 " = busy " 1 " = ready

Notes:

- 1. bit24: Only UHS-I card supports this bit.
- 2. bit30 : This bit is valid only when the card power up status bit is set.
- 3. bit31: This bit is set to LOW if the card has not finished the power up routine.
 - bit 23-4: Describes the SD Card Voltage bit 31 indicates the card power up status. Value "1" is set after power up

5.2.2 CID Register

The CID (Card Identification) register is 128-bit width. It contains the card identification information. The Value of CID Register is vender specific.

Table 5-3: CID register

Field	Width	CID-		Initial Value		Comment
rieiu	wiatii	slice	32GB	64GB	128GB	Comment
MID	8	[127:120]		0x02		Manufacture ID(0x02 = Toshiba)
OID	16	[119:104]		0x544D		OEM/Application ID (0x544D("TM") = Toshiba)
						32GB:"UC0D5"
PNM	40	[103:64]	0x5543304435	0x5543304535	0x5543304635	64GB:"UC0E5"
						128GB:"UC0F5"
PRV	8	[63:56]		0x52		Product Revision
PSN	32	[55:24]		0xnnnnnnnn		Product serial number
-	4	[23:20]		0x0		reserved
MDT	12	[19:8]		0xmmm		Manufacturing data
CRC	7	[7:1]		CRC		CRC 7 Checksum
-	1	[0:0]		0x1		not used, always 1

5.2.3 CSD Register

CSD is Card-Specific Data register provides information on 128bit width. Some field of this register can writable by PROGRAM_CSD (CMD27).

Table 5-4: CSD register

Field	Field Width Cell CSD- Initial Value Type Slice 32GB 64GB 128GB		Comment					
CSD_STR UCTURE		2	R	[127:126]				CSD version 2.0(High Capacity and Extended Capacity)
-		6	R	[125:120]		00_0000	b	reserved
TAAC		8	R	[119:112]	0	0000_1110b		1ms(time unit) * 1.0(time value) = 1ms
NSAC		8	R	[111:104]	0	000_000	0b	0 clock Cycle
	SDR104				0010_1	1011b		200Mbit/s
	SDR50				0000_1	l011b		100Mbit/s
	DDR50				0000_1	1011b		100Mbit/s
TRAN_SPEED	SDR25	8	R	[103:96]	0101_1	1010b		50Mbit/s
	SDR12				0011_0	010b		25Mbit/s
	HS				0101_1010b			50Mbit/s
	DS				0011_0010b			25Mbit/s
CCC		12	R	[95:84]	0101_1011_0101b)101b	Class 0,2,4,5,7,8,10 are supported
READ_BL_	LEN	4	R	[83:80]		1001b		512Bytes

Field	Width	Cell	CSD-	Initial Va		Comment
		Туре	slice	32GB 64GB	128GB	
READ_BL_PARTIAL	1	R	[79:79]	0		" 0 ": Partial block read is inhibited and only unit of block access is allowed.
WRITE_BLK_MISALIG N	1	R	[78:78]	0		" 0 " : Not allowed on this card
READ_BLK_MISALIGN	1	R	[77:77]	0		" 0 " : Invalid on this card
DSR_IMP	1	R	[76:76]	0		" 0 " :DSR NOT implemented
-	6	R	[75:70]	00_0000)b	reserved
C_SIZE	22	R	[69:48]	EE87h 1DD17h	3B9EFh	memory capacity = (C_SIZE+1) * 512K byte
-	1	R	[47:47]	0		reserved
ERASE_BLK_EN	1	R	[46:46]	1		" 1 " :Can erase by WRITE_BL_LEN unit (512 Bytes)
SECTOR_SIZE	7	R	[45:39]	111_111	1b	This size of an erasable sector. This field is fixed to 7F-h. Sector size = 64KBytes.
WP_GRP_SIZE	7	R	[38:32]	000_000	0b	This size of a write protected group. This field is fixed to 00-h. 1 Write Protect Group = 1sector.
WP_GRP_ENABLE	1	R	[31:31]	0		value of 0 means no group write protection possible.
-	2	R	[30:29]	00b		reserved
R2W_FACTOR	3	R	[28:26]	010b		This field is fixed to "2-h", which indicates 4 multiples. However, host should not use this factor and should use 250ms for write timeout.
WRITE_BL_LEN	4	R	[25:22]	1001b		" 9 ": 512Bytes on this card.
WRITE_BL_PARTIAL	1	R	[21:21]	0		" 0 ": Only the WRITE_BL_LEN size or 512Bytes are available
-	5	R	[20:16]	0_0000	b	reserved
FILE_FORMAT_GRP	1	R	[15:15]	0		This field is set to "0". Host should not use this field.
COPY	1	R/W	[14:14]	0		" 0 " : Original on this card
PERM_WRITE_PROTE CT	1	R/W	[13:13]	0		" 0 ": Not protected / Writable on this card
TMP_WRITE_PROTEC	1	R/W	[12:12]	0		" 0 ": Not protected / Writable on this card
FILE_FORMAT	2	R	[11:10]	00b		" 0 ": Hard disk-like file system with partition table on this card.
-	2	R	[9:8]	00b		reserved
CRC	7	R/W	[7:1]	CRC		CRC 7 Checksum
-	1	-	[0:0]	1		not used, always 1

Notes:

1.Cell Types: R: Read Only, R/W: Writable and Readable, R/W(1): One-time Writable / Readable 2. Erase of one data block is not allowed in this card. This information is indicated by "ERASE_BLK_EN". Host System should refer this value before one data block size erase.

5.2.4 RCA Register

The writable 16bit relative card address register carries the card address in SD Card mode.

5.2.5 DSR Register

This register is not used

5.2.6 SCR Register

CR(SD Card Configuration Register) provides information on SD Memory Card's special features. The size of SCR Register is 64 bit.

Table 5-5: The SCR Fields

Field	Width	SCR- slice	Initial Value 32GB <mark>64GB</mark> 128GB		Comment
SCR_STRUCTURE	4	[63:60]		0x0	SCR version 1.0(Version 1.01-3.00)
SD_SPEC	4	[59:56]		0x2	" 2 " : Version 2.00 or Version 3.0X, Version 4.xx (Refer to SD_SPEC3 and SD_SPEC4)
DATA_STAT_AFTER_ERASE	1	[55:55]		0x1	" 1 " : on this card
SD_SECURITY	3	[54:52]	0x3	0x4	"3": Security Version 2.00 "4": Security Version 3.00
SD_BUS_WIDTHS	4	[51:48]		0x5	" 0101 ": 1 and 4 bit supported
SD_SPEC3	1	[47:47]		0x1	" 1 " : Version 3.0X, Version 4.xx (Refer to SD_SPEC4)
EX_SECURITY	4	[46:43]		0x0	Extended Security is not supported.
SD_SPEC4	1	[42:42]		0x1	" 1 " : Version 4.xx
-	6	[41:36]	0x0		reserved
CMD_SUPPORT	4	[35:32]		0x3	" 11 " : CMD23 and CMD20 support
-	32	[31:0]	0>	(3202nnnn	reserved for manufacture usage

5.2.7 Card Status

This field is intended to transmit the card's status information to the host.

Table 5-6: Card Status

Identifier	Bits	Type Value
OUT_OF_RANGE	31	ERX "0" = no error, "1" = error
ADDRESS_ERROR	30	ERX "0" = no error, "1" = error
BLOCK_LEN_ERROR	29	ERX " 0 " = no error, " 1 " = error

Identifier	Bits	Туре	Value			
ERASE_SEQ_ERROR	28	ΕR	" 0 " = no error , " 1 " = error			
ERASE_PARAM	27	E R X	0 " = no error , " 1 " = error			
WP_VIOLATION	26	E R X	" 0 " = not protected , " 1 " = protected			
CARD_IS_LOCKED	25	SX	" 0 " = card unlocked , " 1 " = card locked			
LOCK_UNLOCK_FAILED	24	E R X	" 0 " = no error , " 1 " = error			
COM_CRC_ERROR	23	ΕR	" 0 " = no error , " 1 " = error			
ILLEGAL_COMMAND	22	ΕR	" 0 " = no error , " 1 " = error			
CARD_ECC_FAILED	21	E R X	" 0 " = success , " 1 " = failure			
CC_ERROR	20	E R X	" 0 " = no error , " 1 " = error			
ERROE	19	E R X	" 0 " = no error , " 1 " = error			
-	18		reserved			
-	17		eserved for DEFERRED_RESPONSE			
CSD_OVERWRITE	16	E R X	0 " = no error , " 1 " = error			
WE_ERASE_SKIP	15	E R X	" 0 " = not protected , " 1 " = protected			
CARD_ECC_DISABLED	14	SX	" 0 " = enabled , " 1 " = disabled			
ERASE_STATE	13	SR	" 0 " = cleared , " 1 " = set			
CURRENT_STATE	12 – 9		" 0 " = idle , " 1 " = ready , " 2 " = ident , " 3 " = stanby " 4 " = tran , " 5 " = data , " 6 " = rcv , " 7 " = prg " 8 " = dis , " 9 – 14 " = reserved " 15 " = reserved for I/O mode			
READY_FOR_DATA	8	SX	" 0 " = not ready , " 1 " = ready			
-	7,6		-			
APP_CMD	5	SR	" 0 " = Disabled , " 1 " = Enabled			
-	4		reserved for SD I/O Card			
AKE_SEQ_ERROR	3	ΕR	" 0 " = no error , " 1 " = error			
-	2		reserved			
-	1,0		reserved			

E: Error bit , S: Status bit , R: Detected and set for actual command response. X: Detected and set during command execution.

5.2.8 SD Status

Table 5-7: SD Status

Field	۱۸۷: مادام	Tyre	SD Status -	Initial Value)	Commont
Field	vviatn	т уре	Status - slice	32GB	64GB 128GB		Comment
					00b		1bit: HS1bit, SD1bit, HSSPI, SPI
DAT_BUS_WIDTH	2	SR	[511:510]	10b			4bit: SDR104, DDR50, SDR50, SDR25, SDR12, HS4bit, SD4bit
SECUERED_MODE	1	SR	[509]		1		Secured Mode
reserved	8		[508:502]	(0x00		reserved
reserved	6		[501:496]	(0x00		reserved
SD_CARD_TYPE	16	SR	[495:480]	0:	x0000		Regular SD RD/WR card
SIZE_OF_PROTECTED_AREA	32	SR	[479:448]	0x05000000	0x08000	0000	32GB:81,920KB 64GB:131,072KB 128GB:131,072KB
SPEED_CLASS	8	SR	[447:440]	0x04			Class10
PERFORMANCE_MOVE	8	SR	[439:432]	0x02 0x00			0x02:2MB/s、0x00:0MB/s
AU_SIZE	4	SR	[431:428]	0x9			0x9:4MB
reserved	4		[427:424]		0x0		reserved
ERASE_SIZE	16	SR	[423:408]	0x0020			32AU
ERASE_TIMEOUT	6	SR	[407:402]	0x01			1sec
ERASE_OFFSET	2	SR	[401:400]	11b			3sec
UHS_SPEED_GRADE	4	SR	[399:396]	0x3			0x3:30MB/sec and above
UHS_AU_SIZE	4	SR	[395:392]	0xC			0xC:16MB
-	80		[391:312]	ALL 0			reserved
-	312		[311:0]	ALL 0			reserved for manufacture

S: Status bit, R: Set based on Command Response

5.2.9 Switch Function Status

Switch function command (CMD6) is used to switch or expand memory card functions. Currently four function groups are defined:

- (1) Access Mode: Selection of SD bus interface speed modes.
- (2) Command System: A specific function can be extended and controlled by a set of shared commands.
- (3) Driver Strength Selection of suitable output driver strength in UHS-I modes depends on host environment.
- (4) Power Limit Selection to limit the maximum power depends on host power supply capability and heat release capability.

Table 5-8: Switch Function Status

			Bus Speed	Set Value	Value			
Description	Width	Width Bits		of Gr4	32GB	64GB	128GB	
				0x0	0x00C8 (0.72W/200mA)	0x00C8 (0.72W/200mA)	0x00C8 (0.72W/200mA)	
				0x1	0x00FA (0.90W/250mA)	0x00FA (0.90W/250mA)	0x00FA (0.90W/250mA)	
			SDR104/ SDR50/ DDR50	0x2	0x00FA (0.90W/250mA)	0x00FA (0.90W/250mA)	0x00FA (0.90W/250mA)	
				0x3	0x00FA (0.90W/250mA)	0x00FA (0.90W/250mA)	0x00FA (0.90W/250mA)	
Maximum Current Consumption	16	[511:496]		0x4	0x00FA (0.90W/250mA)	0x00FA (0.90W/250mA)	0x00FA (0.90W/250mA)	
Concumption			SDR25	0x0~0x4	0x00C8 (0.72W/200mA)	0x00C8 (0.72W/200mA)	0x00C8 (0.72W/200mA)	
			SDR12	0x0~0x4	0x0064 (0.36W/100mA)	0x0064 (0.36W/100mA)	0x0064 (0.36W/100mA)	
			HS	0x0	0x00C8 (0.72W/200mA)	0x00C8 (0.72W/200mA)	0x00C8 (0.72W/200mA)	
			DS	0x0	0x0064 (0.36W/100mA)	0x0064 (0.36W/100mA)	0x0064 (0.36W/100mA)	
Function Gr 6, information.	16	[495:480]	-	-	0x8001			
Function Gr 5, information.	16	[479:464]	-	-	0x8001			
Function Gr4,	16	[463:448]	SDR104- 12 DDR50	-	0x801F			
information.			HS,DS	-		0x8001		
Function Gr3,	16	[447:432]	SDR104- 12 DDR50	-	0x800F			
information.	nformation.		HS,DS	-		0x8001		
Function Gr 2, information.	16	[431:416]	-	-	0x8001			
Function Gr1, information.	16	[415:400]	SDR104- 12 DDR50	-	0x801F			

Description	Width	Bits	Bus Speed	Set Value	Value				
Description	wiatn	DITS	Mode	of Gr4	32GB 64GB 128GB				
			HS,DS	-	0x8003				
Function Gr6, information.	4	[399:396]	-	-	Set Response Value				
Function Gr5, information.	4	[395:392]	-	-	Set Response Value				
Function Gr4, information.	4	[391:388]	-	-	:	Set Response Valu	le		
Function Gr3, information.	4	[387:384]	-	-	:	Set Response Valu	ıe		
Function Gr2, information.	4	[383:380]	-	-	Set Response Value				
Function Gr1, information.	4	[379:376]	-	-	Set Response Value				
Data Structure Version	8	[375:368]	-	-	0x00				
Busy Status of functions in Gr6	16	[367:352]	-	-	0x0000				
Busy Status of functions in Gr5	16	[351:336]	-	-	0x0000				
Busy Status of functions in Gr4	16	[335:320]	-	-	0x0000				
Busy Status of functions in Gr3	16	[319:304]	-	-	0x0000				
Busy Status of functions in Gr2	16	[303:288]	-	-	0x0000				
Busy Status of functions in Gr1	16	[287:272]	-	-	0x0000				
Reserved	272	[271:0]	-	-	ALL 0				

5.3 Logical Format

The SD card is formatted before shipping to be compliant to the SD Card FILE SYSTEM SPECIFICATION. The following parameters may be changed if the host system is not compliant with the SD Card Format Specification. The data of the logical format is described in section 5.3.3 (128GB Card), section 5.3.4 (64GB Card) and section 5.3.5 (32GB Card).

5.3.1 SD card Capacities

Table 5-9: SD Card capacities

	Card Capacities									
Item	32GB		64G	В	128GB					
	Sector	КВ	Sector	КВ	Sector	КВ				
Whole Capacity	62,660,608	31,330,304	125,231,104	62,615,552	250,331,136	125,165,568				
User Data Area Size	62,529,536	31,264,768	125,067,264	62,533,632	250,068,992	125,034,496				
Protected Area Size	131,072	65,536	163,840	81,920	262,144	131,072				

5.3.2 SD card System Information

Table 5-10: SD Card System information

	Item	Card Capacities					
	Item	32GB	64GB	128GB			
User Data Area	Data Boundary unit size (KB)	4,096	16,384	16,384			
Area	Cluster Size (KB)	32	128	128			
Protected	Data Boundary unit size (KB)	16	16	16			
Area	Cluster Size (KB)	16	16	16			

5.3.3 Data of the logical format of a 128GB Card

(Contact Viking)

5.3.4 Data of the logical format of a 64GB Card

(Contact Viking)

5.3.5 Data of the logical format of a 32GB Card

(Contact Viking)

6 SD Specification Compliance

1) Non Supported Registers:

DSR Register (Optional register: PHISYCAL LAYER SPECIFICATION 5.5)

2) Non Supported Functions:

Programmable Card Output Driver (Optional in PHYSICAL LAYER SPECIFICATION 6.5) Card 's Internal Write Protect (Optional in PHYSICAL LAYER SPECIFICATION 4.3.6.)

3) Non Specified Command:

CMD4 SET_DSR CMD28 SET_WRITE_PROT CMD29 CLR_WRITE_PROT CMD30 SEND_WRITE_PROT CMD56 GEN_CMD

7 Reliability Guidance

This reliability guidance is intended to provide some guidance related to using raw NAND flash. Although random bit errors may occur during use, it does not necessarily mean that a block is bad. Generally, a block should be marked as bad when a program status failure or erase status failure is detected. The other failure modes may be recovered by a block erase.

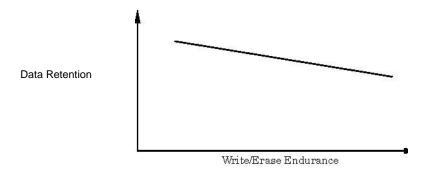
ECC treatment for read data is mandatory due to the following Data Retention and Read Disturb failures.

Write/Erase Endurance

Write/Erase endurance failures may occur in a cell, page, or block, and are detected by doing a status read after either an auto program or auto block erase operation. The cumulative bad block count will increase along with the number of write/erase cycles.

Data Retention

The data in memory may change after a certain amount of storage time. This is due to an electrical charge loss or charge gain. After block erasure and reprogramming, the block may become usable again. Also write/erase endurance deteriorates data retention capability. The figure below shows a generic trend of relationship between write/erase endurance and data retention.



Read Disturb

A read operation may disturb the data in memory. The data may change due to charge gain. Usually, bit errors occur on other pages in the block, not the page being read. After a large number of read cycles (between block erases), a tiny charge may build up and can cause a cell to be soft programmed to another state. After block erasure and reprogramming, the block may become usable again.

Considering the above failure modes, Viking recommends following usage model:

Avoid any excessive iteration of resets and initialization sequences (card identification mode) as far much as possible after power-on, which may result in read disturb failure. The resets include hardware resets and software resets. i.e.

1) The iteration of the following command sequence: CMD0 -ACMD41 (The assertion of ACMD41 implies a count of internal read operation in Raw NAND.

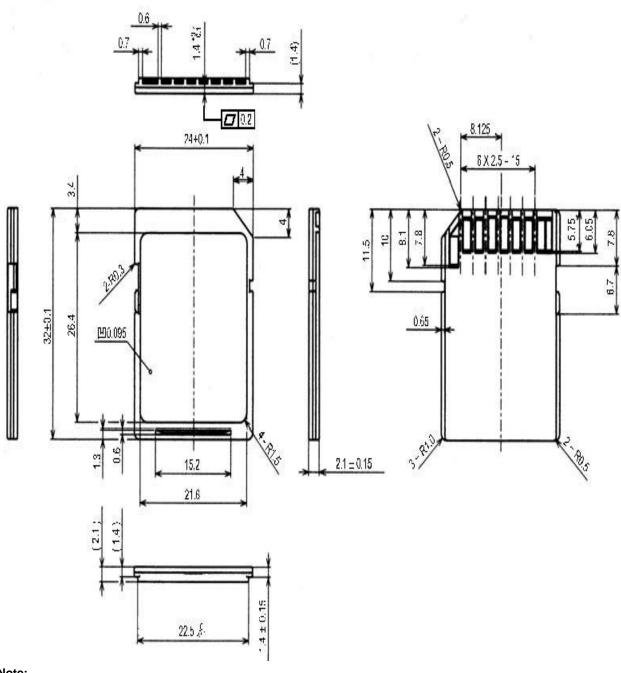
• CMD0: Go idle state command,

• ACMD41 : SD send operation command

2) Iteration of the following command: ACMD43

• ACMD43 : Get MKB command

8 SD Card Mechanical Dimensions



Note:

- 1. All dimensions in mm
- 2. Tolerance is ± 0.15 mm